

# DS-10S

## Selective Soldering Dip Tester



The Dip Tester DS-10S for Selective Soldering Equipment improves process management efficiency by measuring Solder temperature, Soldering time, temperature rising condition, moving speed and solder dimensions a once.

# Special Feature for DS-10S

## ● Solder Temp. Sensor

The sensor part with a small heat capacity accurately measure the solder temperature and atmosphere of the device.

## ● Dip Time Sensor

Detect electrical continuity and measure solder contact time.

## ● Pre-heat Sensor

Temperature sensor temperature rise and peak measurement in the sensor board allows relative control of the device state.

## ● Measurement of Moving Speed

Measure the size of the nozzle by scanning X and Y on two dip time sensors.

## ● Profile Measurement

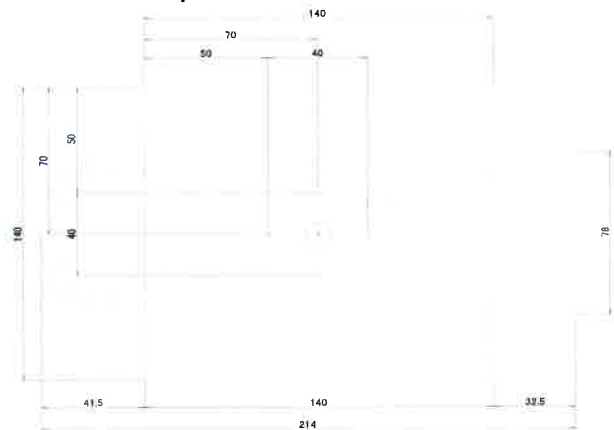
Displays the profile of the solder temperature sensor and preheat sensor.

## ● DS-10S Software

Perform various management such as OK/NG judgment and data analysis.

(Pre-heat temp. Dip time, Solder temp.

X-Y speed, Solder size X, Y and etc.)



## Measurement Data Specifications

Items	Sensor	Display	Measurement range	Accuracy
Solder temp.	K-type sheath thermocouple	Digital LCD 3-digit	0~400°C	±1°C
PCB lower surface temp.	K-type thermocouple		50~300°C	±1°C
Dip time	Electrode (2pcs.)		0~10.0sec.	±0.2sec.
X, Y axis moving speed	Electrode (8pcs.)		0~20mm/sec.	
X, Y axis solder size	Electrode (8pcs.) Calculate from the moving speed & contact time to the electrodes		0~35mm	
Temp. profile	Preheat · Solder temp.	PC software	0~400°C	±2°C

## General Specifications

Items	
Cold contact point compensation	Compensation with platinum temp. measuring resistor
Ambient temp.	150 °C, 5 minutes max.
External connection	USB (mini B connector)
Number of memory	1
Sampling time	50 ms (fix)
Outer dimensions · Weight	214 (D) mm x 78 (W) mm x 43.6 (H) mm · 820g
Power supply	AAA batteries x 2pcs.

The above specifications are subject to change without notice.



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